

ABSTRACT

Provided is curable resin composition which gives a cured article excellent in chemical resistance, dielectric properties, low water-absorption, heat resistance, flame retardance, and mechanical properties and which is usable in applications such as dielectric materials, insulating materials, heat-resistant materials, and structural materials. The curable resin composition includes a component (A) which is a polyphenylene ether oligomer having a number-average molecular weight of 700 to 4,000 and having a vinyl group at both end and a component (B) which is a solvent-soluble polyfunctional vinylaromatic copolymer which has structural units derived from monomers including a divinylaromatic compound (a) and an ethylvinylaromatic compound (b) and in which the content of repeating units derived from the divinylaromatic compound (a) is 20 mol% or higher, the ratio of the amount (wt.%) of the component (A) to that (wt.%) of the component (B) being (20 to 98):(2 to 80). The composition can further contain a layered silicate, a halogenated flame retardant, etc.